

# APT11026JFLL

### **1100V 33A 0.260**Ω

## POWER MOS 7™

FREDFET

Power MOS 7<sup>TM</sup> is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS 7<sup>TM</sup> by significantly lowering R<sub>DS(ON)</sub> and Q<sub>g</sub>. Power MOS 7<sup>TM</sup> combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with APT's patented metal gate structure.

- Lower Input Capacitance
- Lower Miller Capacitance
- Lower Gate Charge, Qg
- Increased Power Dissipation
- Easier To Drive
- Popular SOT-227 Package
- FAST RECOVERY BODY DIODE

#### MAXIMUM RATINGS

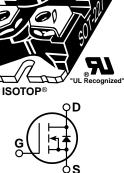
All Ratings: T	<sub>C</sub> = 25°C unless	otherwise s	specified.
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Symbol	Parameter	APT11026JFLL	UNIT
V <sub>DSS</sub>	Drain-Source Voltage	1100	Volts
I <sub>D</sub>	Continuous Drain Current @ T <sub>C</sub> = 25°C	33	A
I <sub>DM</sub>	Pulsed Drain Current <sup>①</sup>	134	- Amps
V <sub>GS</sub>	Gate-Source Voltage Continuous	±30	Valta
V <sub>GSM</sub>	Gate-Source Voltage Transient	±40	- Volts
P <sub>D</sub>	Total Power Dissipation @ T <sub>C</sub> = 25°C	694	Watts
' D	Linear Derating Factor	5.56	W/°C
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to 150	
ΤL	Lead Temperature: 0.063" from Case for 10 Sec.	300	7 ~
I <sub>AR</sub>	Avalanche Current $^{\textcircled{1}}$ (Repetitive and Non-Repetitive)	33	Amps
E <sub>AR</sub>	Repetitive Avalanche Energy ①	50	
E <sub>AS</sub>	Single Pulse Avalanche Energy ④	3600	mJ

#### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage ( $V_{GS} = 0V, I_{D} = 250\mu A$ )	1100			Volts
I <sub>D(on)</sub>	On State Drain Current <sup>(2)</sup> $(V_{DS} > I_{D(on)} \times R_{DS(on)} Max, V_{GS} = 10V)$	33			Amps
R <sub>DS(on)</sub>	Drain-Source On-State Resistance <sup>(2)</sup> $(V_{GS} = 10V, 0.5 I_{D[Cont.]})$			0.260	Ohms
	Zero Gate Voltage Drain Current ( $V_{DS} = V_{DSS}$ , $V_{GS} = 0V$ )			250	μA
DSS	Zero Gate Voltage Drain Current ( $V_{DS} = 0.8 V_{DSS}$ , $V_{GS} = 0V$ , $T_{C} = 125^{\circ}C$ )			1000	μΛ
I <sub>GSS</sub>	Gate-Source Leakage Current ( $V_{GS} = \pm 30V$ , $V_{DS} = 0V$ )			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage ( $V_{DS} = V_{GS}$ , $I_{D} = 5mA$ )	3		5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.



#### DYNAMIC CHARACTERISTICS

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C <sub>iss</sub>	Input Capacitance	$V_{GS} = 0V$		10640		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25V		1605		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1 MHz		302		
Qg	Total Gate Charge <sup>③</sup>	V <sub>GS</sub> = 10V		389		
Q <sub>gs</sub>	Gate-Source Charge	$V_{DD} = 0.5 V_{DSS}$		53		nC
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	I <sub>D</sub> = I <sub>D</sub> [Cont.] @ 25°C		246		
t <sub>d</sub> (on)	Turn-on Delay Time	V <sub>GS</sub> = 15V		21		
t r	Rise Time	$V_{DD} = 0.5 V_{DSS}$		13		ns
t <sub>d</sub> (off)	Turn-off Delay Time	I <sub>D</sub> = I <sub>D</sub> [Cont.] @ 25°C		63		115
t <sub>f</sub>	Fall Time	$R_{G} = 0.6\Omega$		20		

#### SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions		MIN	TYP	MAX	UNIT
۱ <sub>s</sub>	Continuous Source Current (Body Diode)				33	0
I <sub>SM</sub>	Pulsed Source Current <sup>①</sup> (Body Diode)				134	Amps
V <sub>SD</sub>	Diode Forward Voltage $\textcircled{O}$ (V <sub>GS</sub> = 0V, I <sub>S</sub> = -I <sub>D</sub> [Cont.])				1.3	Volts
dv/ <sub>dt</sub>	Peak Diode Recovery <sup>dv/</sup> dt <sup>⑤</sup>				18	V/ns
	Reverse Recovery Time	T <sub>j</sub> = 25°C			310	
t <sub>rr</sub>	(I <sub>S</sub> = -I <sub>D</sub> [Cont.], <sup>di</sup> / <sub>dt</sub> = 100A/µs)	T <sub>j</sub> = 125°C			625	ns
0	Reverse Recovery Charge	T <sub>j</sub> = 25°C		2.0		
Q <sub>rr</sub>	(I <sub>S</sub> = -I <sub>D</sub> [Cont.], di/ <sub>dt</sub> = 100A/µs)	T <sub>j</sub> = 125°C		6.0		μC
I <sub>RRM</sub>	Peak Recovery Current	T <sub>j</sub> = 25°C		15		
	(I <sub>S</sub> = -I <sub>D</sub> [Cont.], <sup>di</sup> / <sub>dt</sub> = 100A/µs)	T <sub>j</sub> = 125°C		26		Amps

#### THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{ extsf{ heta}JC}$	Junction to Case			0.18	
$R_{ extsf{ heta}JA}$	Junction to Ambient			40	°C/W

1 Repetitive Rating: Pulse width limited by maximum junction temperature.

2 Pulse Test: Pulse width < 380 µs, Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

device itself.  $I_{S} \leq -I_{D[Cont.]} \quad di/_{dt} \leq 700 \text{A/}\mu \text{s} \quad V_{R} \leq V_{DSS} \quad T_{J} \leq 150^{\circ}\text{C}$ 

